

**SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE
HAVING A SOLDER COLUMN ARRAY**

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Abstract

A method supports, on a printed circuit board, a circuit package including a substrate having a solder column array. The method comprises providing the circuit package with an over-sized lid that extends outwardly over an edge of the substrate. The circuit package is electrically connected to the printed circuit
10 board via the solder column array and a plurality of supports are secured to the printed circuit board in position underneath the lid of the circuit package while leaving a gap between the lid and the support. A static compressive force is applied and maintained to the circuit package relative to the printed circuit board, thereby causing the solder column array to creep until the gap is closed
15 and a substantial portion of the compressive force is borne by the supports.